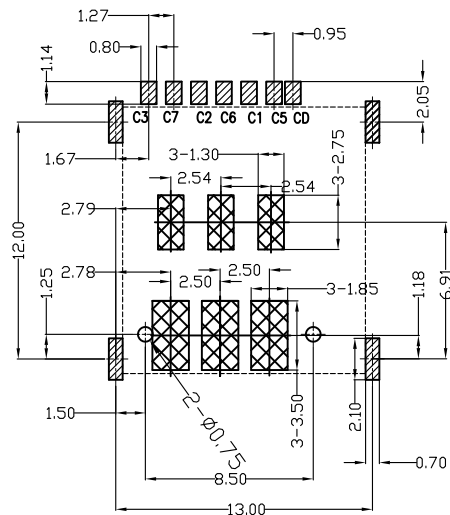
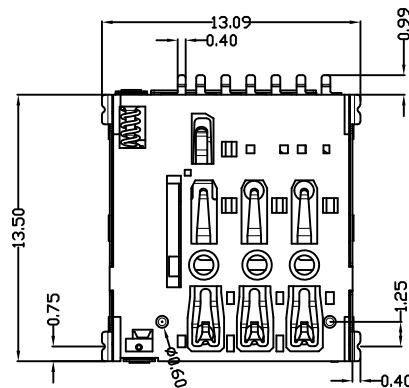
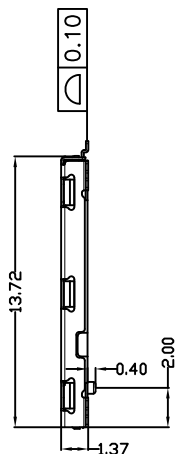
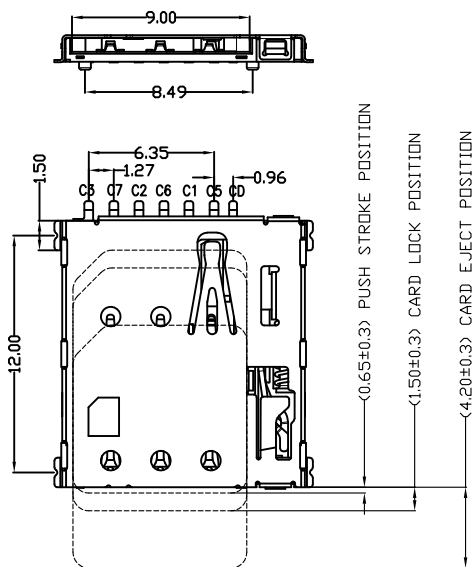
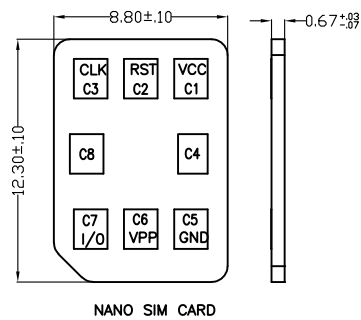


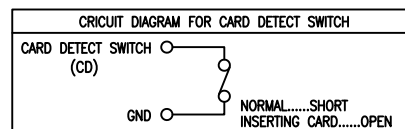


RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ± 0.05

PAD
 KEEP OUT AREA



NANO SIM CARD



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

NOTES:

- 1) MATERIAL:
HOUSING: HI-TEMP. PLASIC UL 94V-0
CONTACT: COPPER ALLOY
SHELL: STAINLESS STEEL
- 2) PLATING :
TERMINAL:
CONTACT AREA: Au GOLD FLASH.
SOLDER AREA: AU GOLD FLASH.
UNDER PLATE: NICKEL.
SHELL: NICKEL PLATED OVER ALL.
SOLDER AREA: GOLD FLASH.
3. SPECIALITY:
3.1 Rated current: 1.0A
3.2 Rated voltage: 30V
3.3 Contact Resistance: 100mΩ MAX
3.4 Insulation Resistance: 1000MΩ MIN 500V DC
3.5 Dielectric withstanding voltage: 500V AC.
3.6 Solder ability: 260±0/-5℃, 30±10s.
3.7 Durability: 5000 Cycles Min.
3.8 Operating condition: Temperature -40℃~+85℃;
Humidity 80% R.H MAX



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TOLERANCE: X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X." ± 2 " X.X" ± 0.5 "	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: NANO SIM PUSH 1.37H 带CD PIN 带柱	
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYCW364-SIM07-137B	MOLD NO.
UNIT: mm [inch] SCALE: 1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2406011736	SHEET NO. 1 OF 1